

## ABSTRACT

The present invention provides An apparatus for supporting supports, during a testing operation, a leadframe formed with at least one row of non-singulated semiconductor devices. The apparatus ~~comprises~~ includes a main body and a leadframe support member, and the leadframe support is formed with at least one groove for receiving semiconductor devices such that in use leads extending from said the semiconductor devices lie on a surface of said the support member. The invention also relates to a system for transporting devices to and from a test probe head